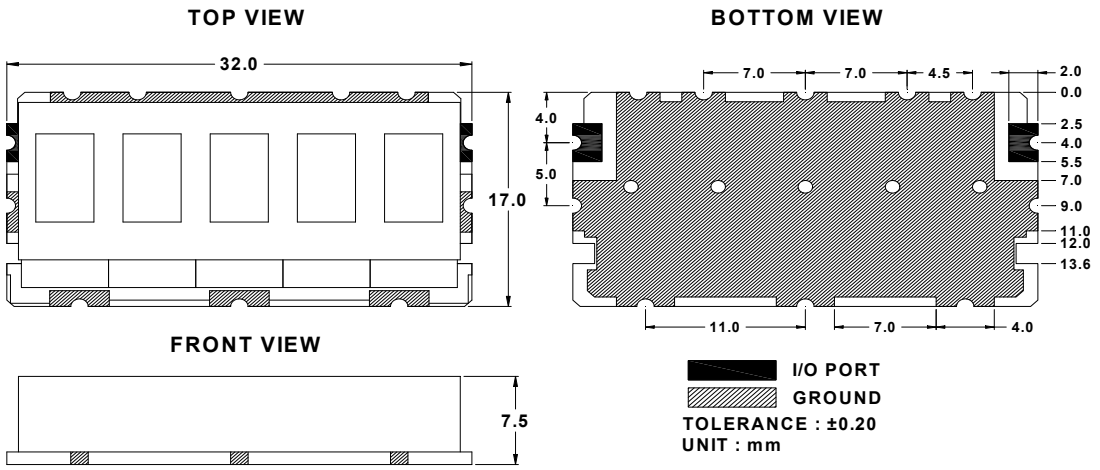
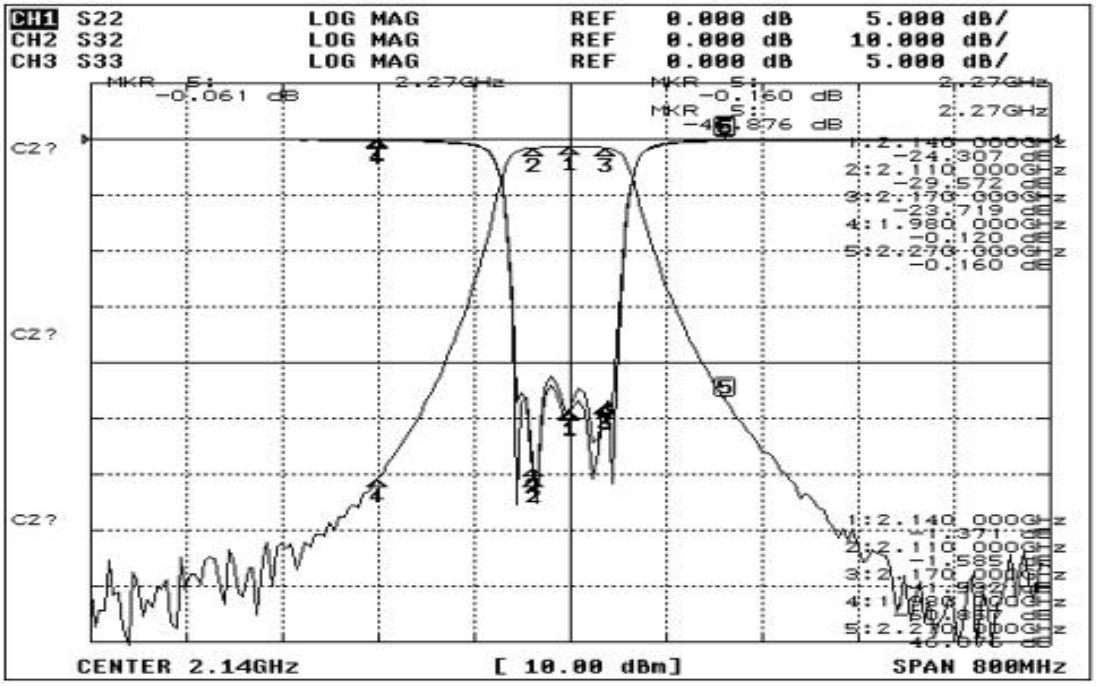
Electrical Specification

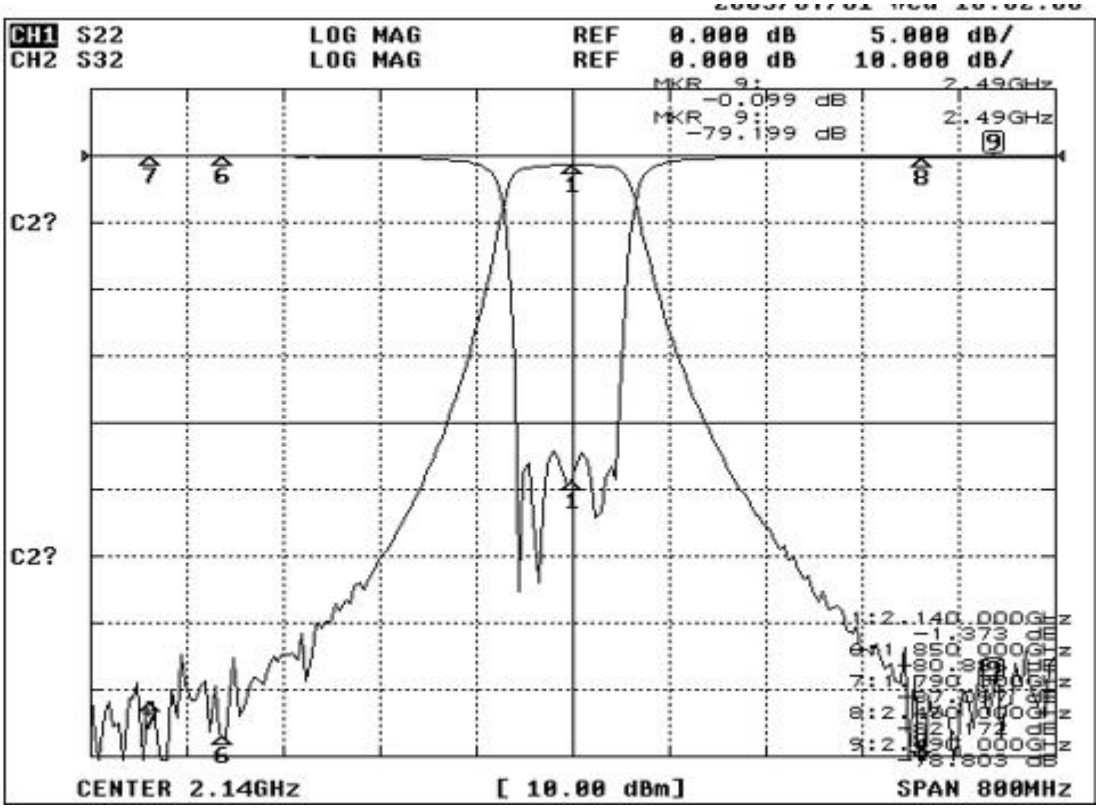
ITEMS	SPEC	UNIT
Center Frequency [fo]	2140	MHz
Bandwidth [BW]	fo ±30.0 [2110 ~ 2170]	MHz
Insertion Loss in BW	2.0	dB max
Ripple in BW	0.5	dB max
Return Loss in BW	15.0	dB min
Attenuation ☑ Absolute Value ☐ Relative Value	45dBc min @ fo ± [1980]	MHz
	60dBc min @ fo ± [1850]	MHz
	35dBc min @ fo ± [1790]	MHz
	35dBc min @ fo ± [2270]	MHz
	60dBc min @ fo ± [2430]	MHz
	60dBc min @ fo ± [2490]	MHz
Group Delay Variation		ns max
Input Power	3	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40℃ to +85℃	

Mechanical Specification

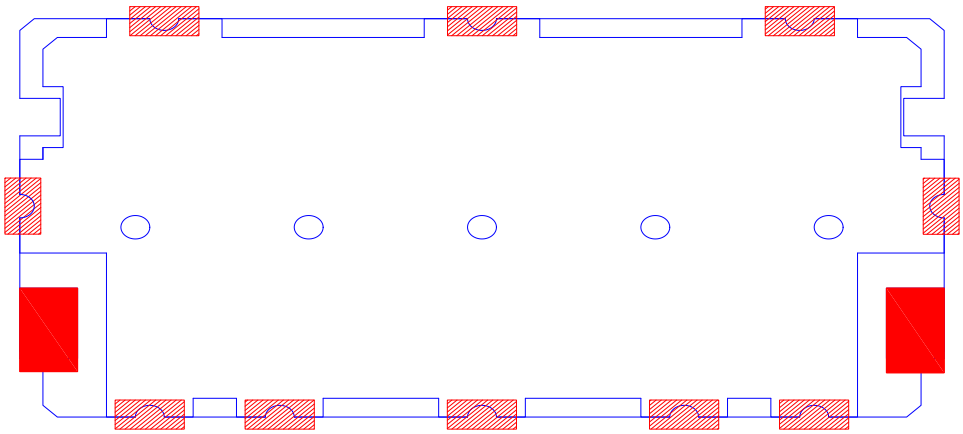


Plot Data


CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
CH3 S33 LOG MAG REF 0.000 dB 5.000 dB/
MKR 5: 2.27GHz
-0.061 dB
MKR 5: 2.27GHz
-0.160 dB
C2?
C2?
C2?
1:2.140 000GHz
-24.307 dB
2:2.110 000GHz
-29.572 dB
3:2.170 000GHz
-23.719 dB
4:1.980 000GHz
-0.120 dB
5:2.270 000GHz
-0.160 dB
CENTER 2.14GHz
[10.00 dBm]
SPAN 800MHz


CH1 S22 LOG MAG REF 0.000 dB 5.000 dB/
CH2 S32 LOG MAG REF 0.000 dB 10.000 dB/
MKR 9: 2.49GHz
-0.099 dB
MKR 9: 2.49GHz
-79.199 dB
C2?
C2?
1:2.140 000GHz
-1.373 dB
CENTER 2.14GHz
[10.00 dBm]
SPAN 800MHz

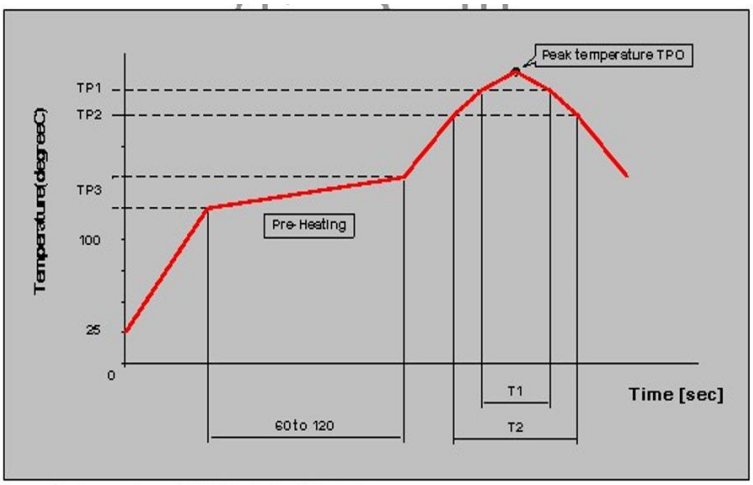
Recommanded PC Board Pattern



GROUND SOLDERING POINT

I/O PORT SOLDERING POINT

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180